## Plastic Medium-Power Complementary Silicon Transistors

Designed for general-purpose amplifier and low-speed switching applications.

#### Features

• High DC Current Gain -

 $h_{FE} = 2500 (Typ) @ I_C$ = 4.0 Adc

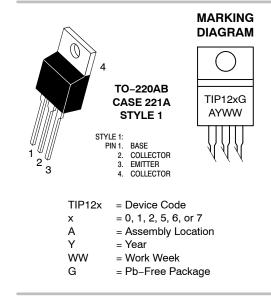
- Collector-Emitter Sustaining Voltage @ 100 mAdc
  - $V_{CEO(sus)} = 60 \text{ Vdc} (Min) TIP120, TIP125$ 
    - = 80 Vdc (Min) TIP121, TIP126
    - = 100 Vdc (Min) TIP122, TIP127
- Low Collector-Emitter Saturation Voltage -
  - $V_{CE(sat)} = 2.0 \text{ Vdc} (Max) @ I_C = 3.0 \text{ Adc}$
  - $= 4.0 \text{ Vdc} (\text{Max}) @ I_{\text{C}} = 5.0 \text{ Adc}$
- Monolithic Construction with Built-In Base-Emitter Shunt Resistors
- Pb–Free Packages are Available\*



#### **ON Semiconductor®**

www.onsemi.com

DARLINGTON 5 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 60–80–100 VOLTS, 65 WATTS



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 3 of this data sheet.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### MAXIMUM RATINGS

Rating	Symbol	TIP120, TIP125	TIP121, TIP126	TIP122, TIP127	Unit	
Collector-Emitter Voltage	V <sub>CEO</sub>	60 80 100			Vdc	
Collector-Base Voltage	V <sub>CB</sub>	60	80	100	Vdc	
Emitter-Base Voltage	V <sub>EB</sub>		5.0			
Collector Current – Continuous – Peak	Ι <sub>C</sub>		5.0 8.0			
Base Current	IB		120			
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	PD		65 0.52			
Total Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	PD	2.0 0.016			W W/°C	
Unclamped Inductive Load Energy (Note 1)	E	50			mJ	
Operating and Storage Junction, Temperature Range	TJ, T <sub>stg</sub>	-65 to +150			°C	

#### **THERMAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ ext{ heta}JC}$	1.92	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	62.5	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1.  $I_C = 1 \text{ A}, L = 100 \text{ mH}, \text{ P.R.F.} = 10 \text{ Hz}, V_{CC} = 20 \text{ V}, R_{BE} = 100 \Omega$ 

ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit		
DFF CHARACTERISTICS							
Collector–Emitter Sustaining Voltage (Note 2) $(I_C = 100 \text{ mAdc}, I_B = 0)$	TIP120, TIP125	V <sub>CEO(sus)</sub>	60	-	Vdc		
	TIP121, TIP126 TIP122, TIP127		80 100				
Collector Cutoff Current		I <sub>CEO</sub>			mAdc		
(V <sub>CE</sub> = 30 Vdc, I <sub>B</sub> = 0)	TIP120, TIP125		-	0.5			
(V <sub>CE</sub> = 40 Vdc, I <sub>B</sub> = 0)	TIP121, TIP126		-	0.5			
(V <sub>CE</sub> = 50 Vdc, I <sub>B</sub> = 0)	TIP122, TIP127		-	0.5			
Collector Cutoff Current		I <sub>CBO</sub>			mAdc		
(V <sub>CB</sub> = 60 Vdc, I <sub>E</sub> = 0)	TIP120, TIP125		-	0.2			
(V <sub>CB</sub> = 80 Vdc, I <sub>E</sub> = 0)	TIP121, TIP126		-	0.2			
(V <sub>CB</sub> = 100 Vdc, I <sub>E</sub> = 0)	TIP122, TIP127		-	0.2			
Emitter Cutoff Current ( $V_{BE}$ = 5.0 Vdc, $I_C$ = 0)		I <sub>EBO</sub>	-	2.0	mAdc		
ON CHARACTERISTICS (Note 2)							
DC Current Gain (I <sub>C</sub> = 0.5 Adc, V <sub>CE</sub> = 3.0 Vdc) (I <sub>C</sub> = 3.0 Adc, V <sub>CE</sub> = 3.0 Vdc)		h <sub>FE</sub>	1000 1000		-		
Collector, Emitter Seturation Voltage		Mana a	1	1	Vda		

(I <sub>C</sub> = 3.0 Adc, V <sub>CE</sub> = 3.0 Vdc)		1000	-	
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>			Vdc
(I <sub>C</sub> = 3.0 Adc, I <sub>B</sub> = 12 mAdc)		-	2.0	
(I <sub>C</sub> = 5.0 Adc, I <sub>B</sub> = 20 mAdc)		-	4.0	
Base-Emitter On Voltage (I <sub>C</sub> = 3.0 Adc, V <sub>CE</sub> = 3.0 Vdc)	V <sub>BE(on)</sub>	-	2.5	Vdc

#### DYNAMIC CHARACTERISTICS

Small–Signal Current Gain ( $I_C$ = 3.0 Adc, $V_{CE}$ = 4.0 Vdc, f = 1.0 MHz)		4.0	-	-
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 0.1 MHz TIP125, TIP126, TIP127 TIP120, TIP121, TIP122			300 200	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2%

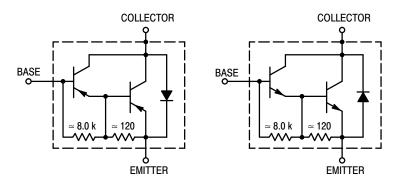


Figure 1. Darlington Circuit Schematic

#### **ORDERING INFORMATION**

Device	Package	Shipping
TIP120	TO-220	50 Units / Rail
TIP120G	TO-220 (Pb-Free)	50 Units / Rail
TIP121	TO-220	50 Units / Rail
TIP121G	TO-220 (Pb-Free)	50 Units / Rail
TIP122	TO-220	50 Units / Rail
TIP122G	TO-220 (Pb-Free)	50 Units / Rail
TIP125	TO-220	50 Units / Rail
TIP125G	TO-220 (Pb-Free)	50 Units / Rail
TIP126	TO-220	50 Units / Rail
TIP126G	TO-220 (Pb-Free)	50 Units / Rail
TIP127	TO-220	50 Units / Rail
TIP127G	TO-220 (Pb-Free)	50 Units / Rail

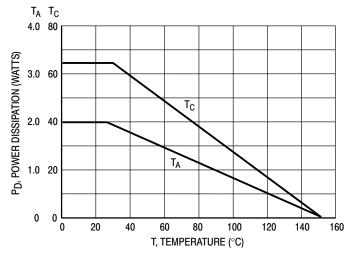


Figure 2. Power Derating

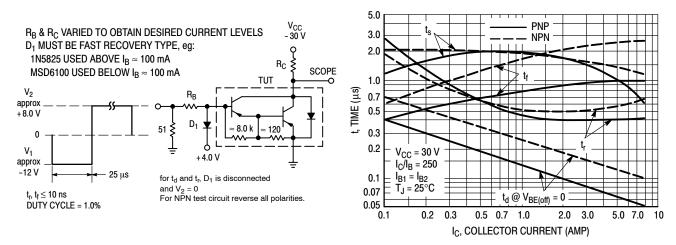


Figure 3. Switching Times Test Circuit

Figure 4. Switching Times

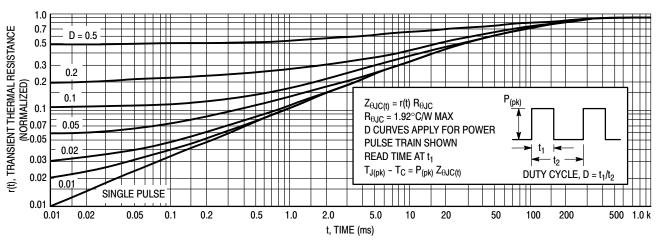


Figure 5. Thermal Response

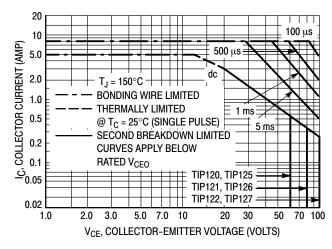


Figure 6. Active-Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C$  –  $V_{CE}$  limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on  $T_{J(pk)} = 150^{\circ}C$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} < 150^{\circ}C$ .  $T_{J(pk)}$  may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown

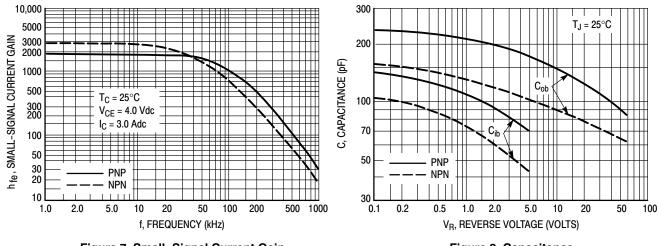
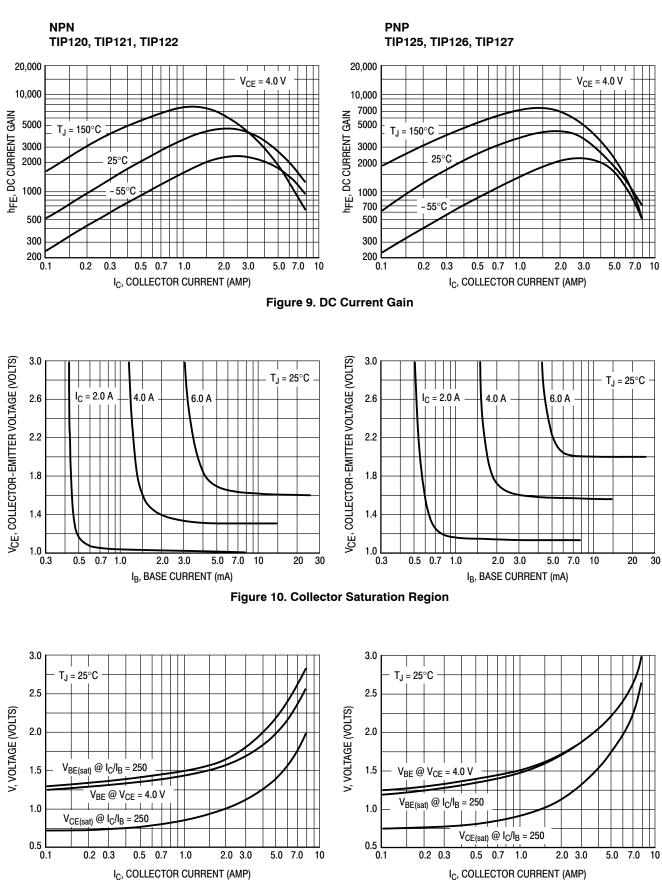
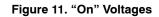


Figure 7. Small–Signal Current Gain

Figure 8. Capacitance





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				4. MAX V	WIDTH FOR	F102 DEVICE	= 1.3510101		
	I	Γ I			INC	HES	MILLIM	ETERS	
				DIM	MIN.	MAX.	MIN.	MAX.	
	2 3			А	0.570	0.620	14.48	15.75	
<u> </u>	┟┰┟┟╌┙──┼			В	0.380	0.415	9.66	10.53	
⊢	₩+₩++			С	0.160	0.190	4.07	4.83	
	í lí	f I		D	0.025	0.038	0.64	0.96	
' z –	I I K			F	0.142	0.161	3.60	4.09	
	î î			G	0.095	0.105	2.42	2.66	
				н	0.110	0.161	2.80	4.10	
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G	J-	╼║╼		N	0.045	0.060	4.83	1.52 5.33	
Ŭ,	' → → D			Q	0.190	0.210	2.54	3.04	
_	N -			R	0.080	0.120	2.54	2.79	
				s	0.030	0.055	1.15	1.41	
				т	0.235	0.255	5.97	6.47	
				U U	0.000	0.050	0.00	1.27	
				v	0.045		1.15		
				z		0.080		2.04	
2. 3. 4. STYLE 5: PIN 1. 2. 3. 4. STYLE 9: PIN 1. 2. 3.	BASE         PIN 1.           COLLECTOR         2.           EMITTER         3.           COLLECTOR         4.           GATE         PIN 1.           DRAIN         2.           SOURCE         3.           DRAIN         2.           GATE         PIN 1.           CALL         STYLE 10           GATE         PIN 1.           COLLECTOR         2.           EMITTER         3.	BASE EMITTER COLLECTOR EMITTER ANODE CATHODE CATHODE CATHODE	2. 3. 4. STYLE 7: PIN 1. 2. 3. 4. STYLE 11: PIN 1. 2. 3.		E E	2. MA 3. GA 4. MA STYLE 8: PIN 1. CA 2. AN 3. EX 4. AN STYLE 12: PIN 1. MA 2. MA 3. GA	IN TERMINAL THODE DDE TERNAL TRIP DDE IN TERMINAL IN TERMINAL	2 2 /DELAY .2	

 
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